



# High Resolution Cross Strip Anodes for Photon Counting detectors

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# Cross Strip Anode Configuration

Cross strip readout is a multilayer anode with  $\sim 0.5\text{mm}$  period strip sets in orthogonal directions. This is comparable to cross delay line anodes, however without the delay line, Instead each strip is connected to an amplifier.

**Cross strip is a multi-layer cross finger layout.**

**Fingers have  $\sim 0.5\text{mm}$  period on ceramic.**

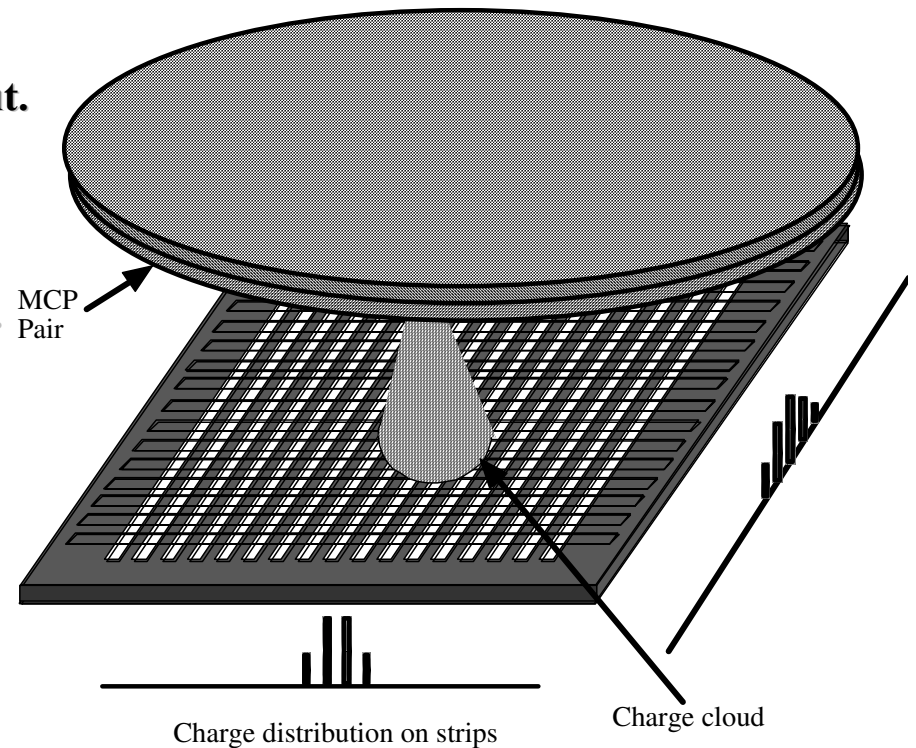
**Charge spread over 5 strips per axis,**

**Event position derived from charge centroid.**

**Can encode multiple simultaneous events.**

**Fast event propagation (few ns).**

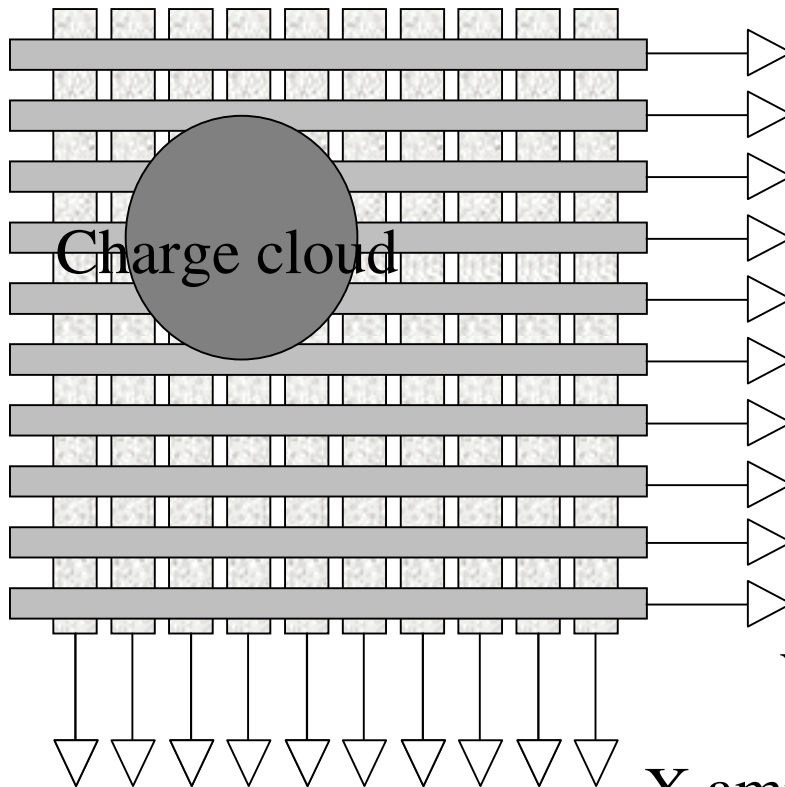
**Compact and robust ( $900^\circ\text{C}$ ).**





# High Resolution Cross Strip Anodes

Collector strips



**Fingers have  $\sim 0.5\text{mm}$  period on ceramic.**

**Charge spread over 5 strips per axis**

**Lower strips are exposed 50%**

**Upper strips cover other 50%**

**Connect amps to each strip**

**Use ASIC multi amplifier chips**

Y amplifiers

X amplifiers



# Cross Strip Anode Configuration

## Initial 8 x 8 mm test XS anode

0.5mm period, all metal/ceramic

Onboard wire-bonded preamplifier chips.

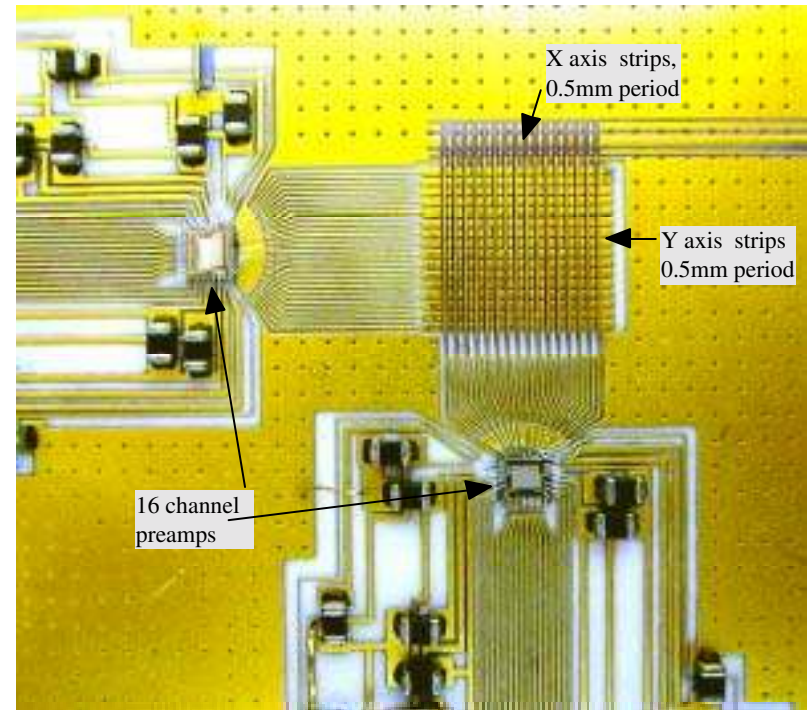
External amp, digitization and software centroid

### Cross Strip Scheme Characteristics

- Low MCP gain (few  $\times 10^6$ )
- Resolutions  $< 10\mu\text{m}$  FWHM
- Linear images (few  $\mu\text{m}$  nonlinearity)
- Compact & robust ( $900^\circ\text{C}$  capable)
- Very fast signal propagation ( $\sim 1\text{ns}$ )

### Future potential advances

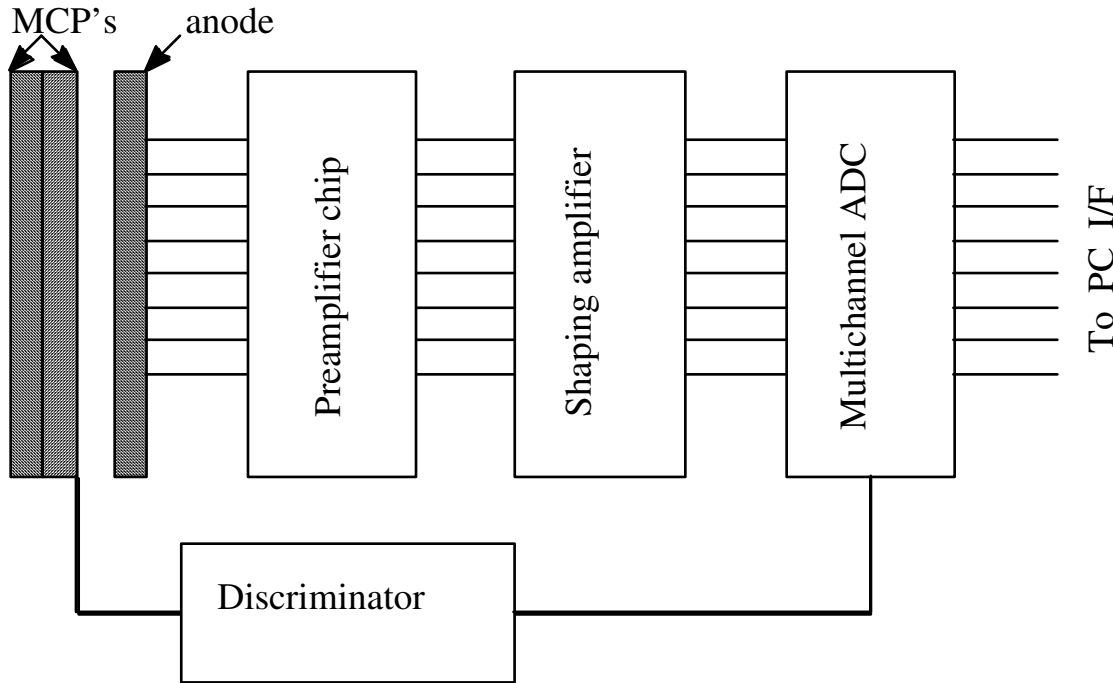
- Large formats  $> 50\text{mm}$  possible
- Small, low power ASIC encoding
- High event rates ( $> 1\text{MHz}$ )
- Multiple simultaneous event capable



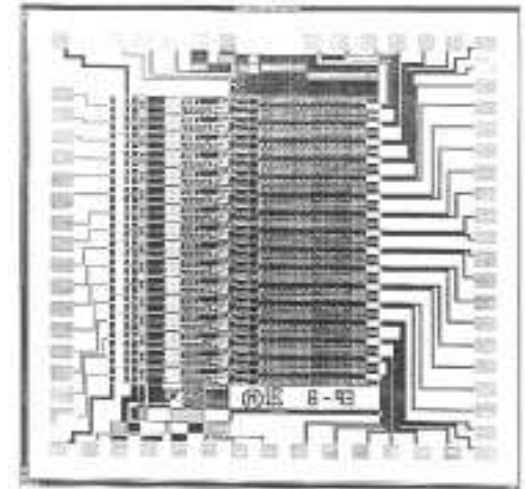
**Photo of the 8 x 8mm test XS anode with its wire-bonded preamplifier chips.**



# Cross Strip Anode Electronics Chain



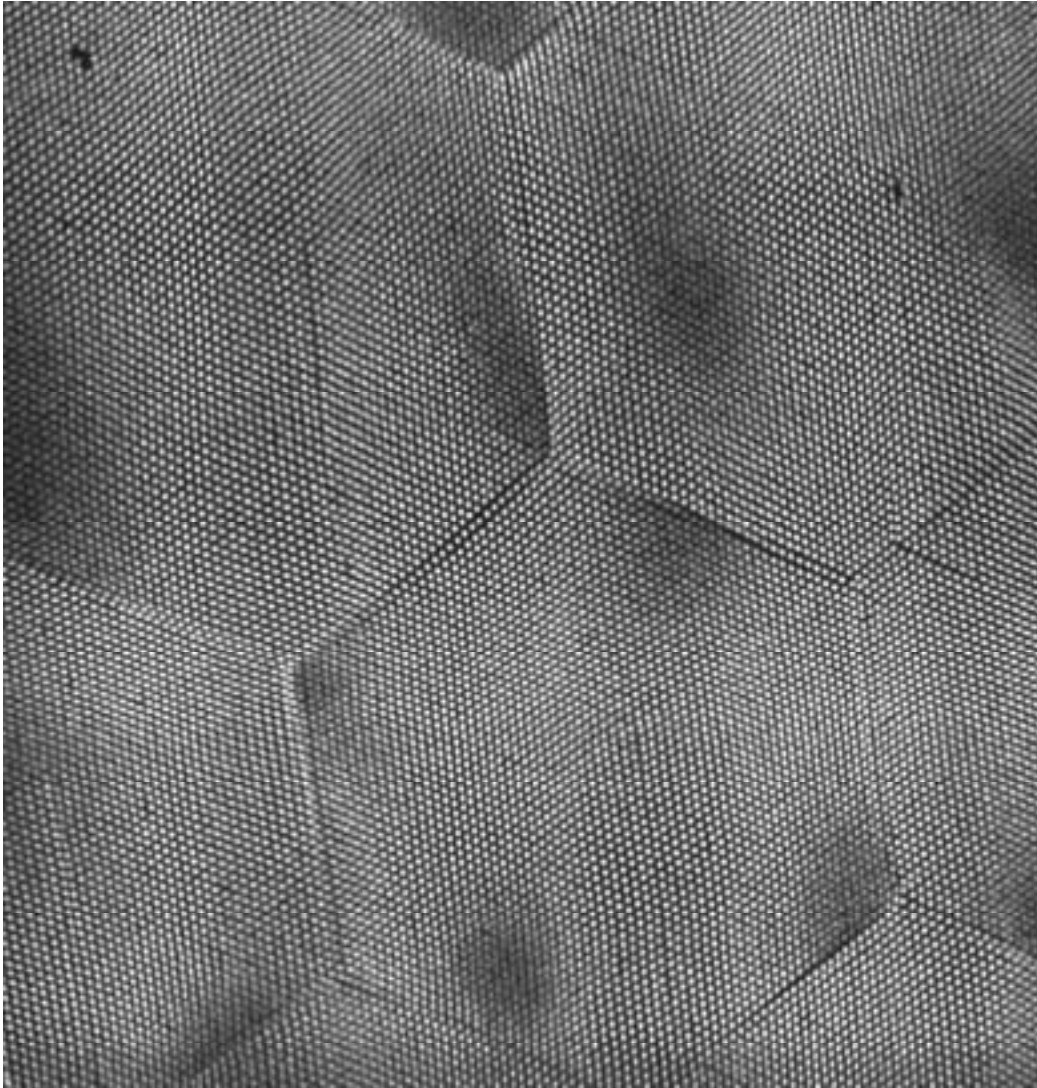
**Schematic of the cross strip anode position encoding electronics test-bed system. All signals amplified and digitized. Choose up to 12 bits per signal. Slow ADC's (10 $\mu$ s per digitization) using standard lab electronics, but sufficient for evaluation tests and flexible to select & diagnose parameter dependence.**



**ICD-2 preamplifier (16 ch) chip design that is being used for the current tests on the XS. ~1500e<sup>-</sup> rms noise, <20ns output, 10mW/ch.**



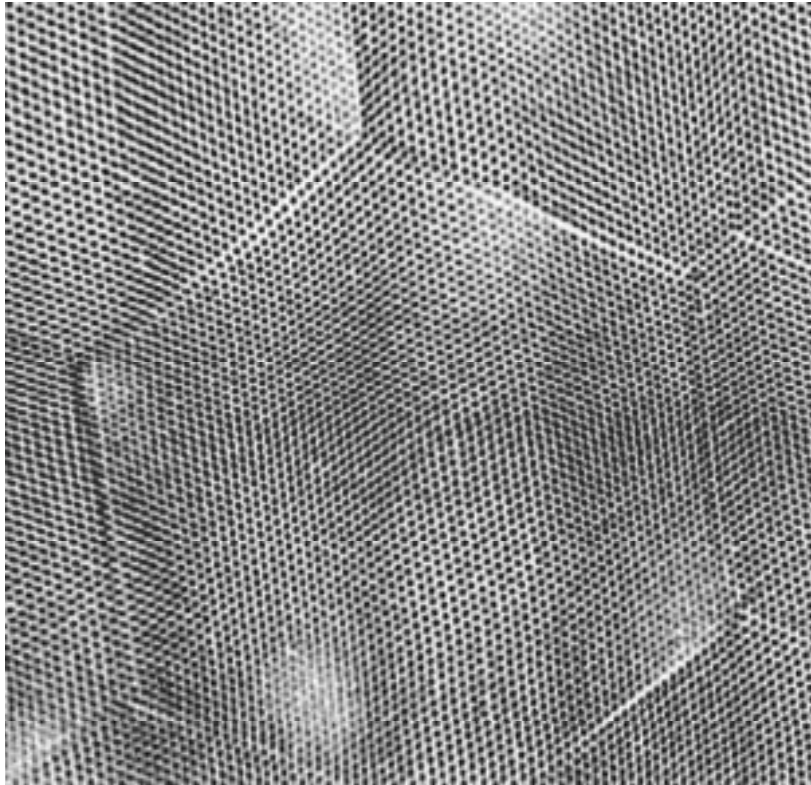
# Initial Images with 12 $\mu$ m MCP Pair and Cross Strip Anode



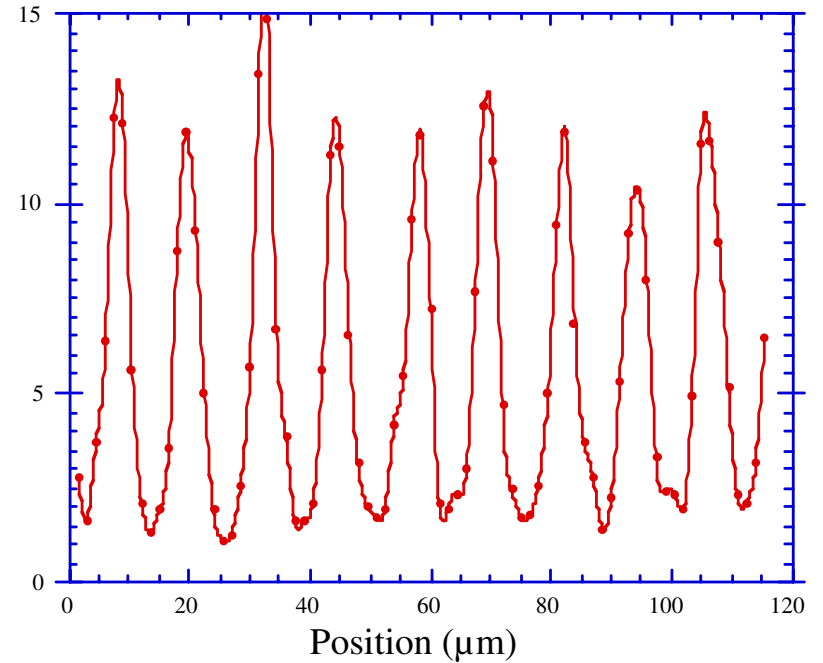
**2 x 2 mm area imaged by cross strip anode. 12 $\mu$ m pore MCP's in a back to back pair with  $\sim 5 \times 10^6$  gain. Shows MCP multi-fiber modulation, dead pores, pore misalignments, and Moire beat modulation between the MCP's.**



# 12 $\mu$ m MCP Detector Image Resolution



**Image section of a 12 $\mu$ m pore MCP pair obtained at  $5 \times 10^6$  gain with the XS anode.**



**An image histogram slice of the 12 $\mu$ m pore MCP image showing the significant level of modulation.**



# 10 $\mu$ m MCP Detector Image Resolution

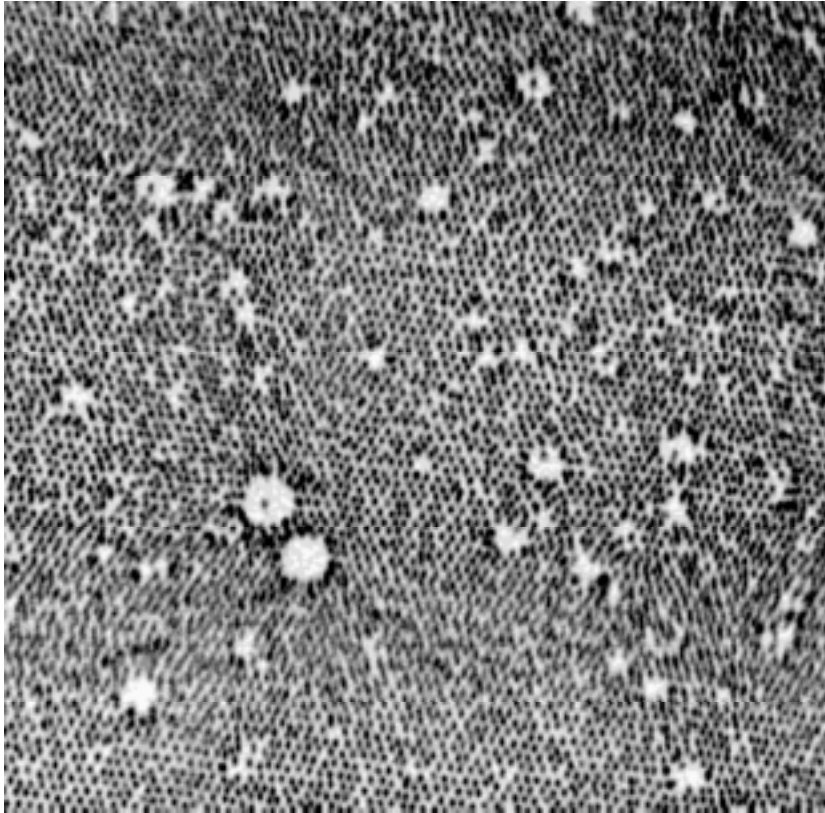


Image detail of a 10 $\mu$ m pore MCP pair obtained at  $2 \times 10^6$  gain with the XS anode shows the defective MCP material.

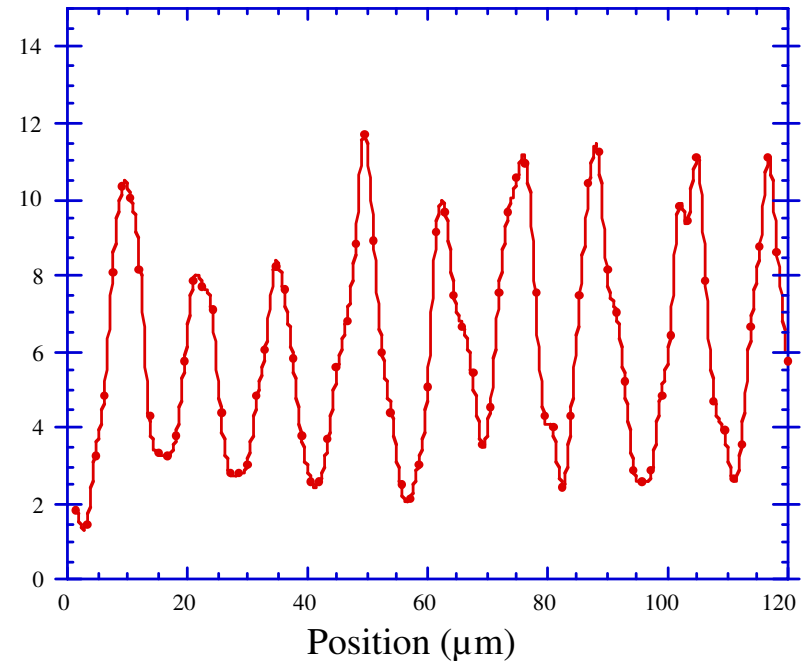
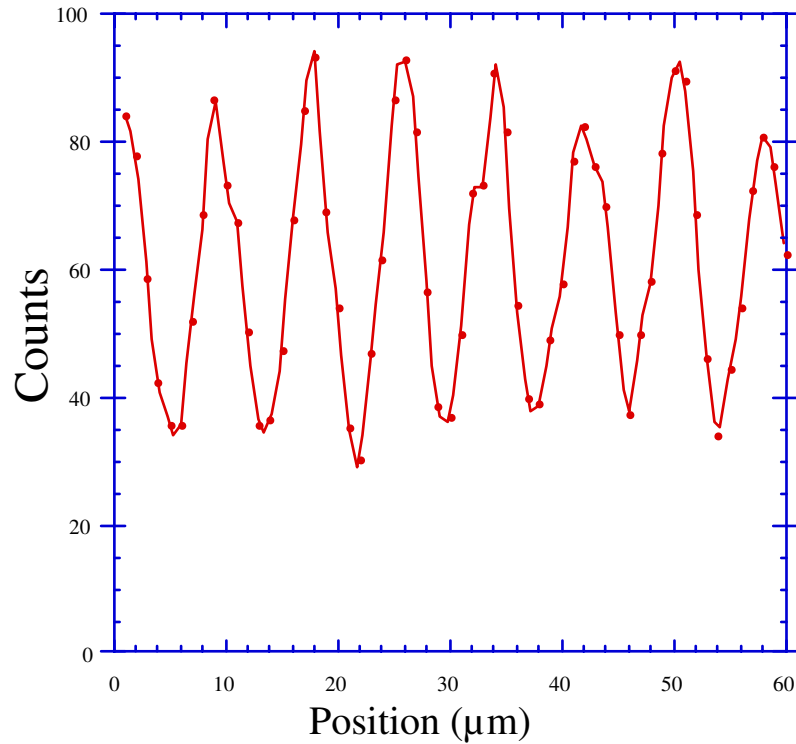


Image histogram slice of the 10 $\mu$ m pore MCP image showing the significant level of modulation.

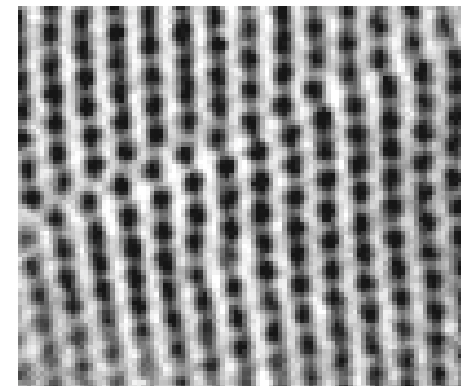
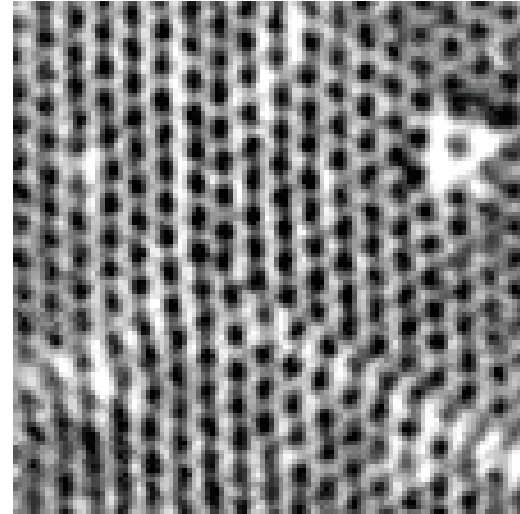




# 7 $\mu$ m MCP Detector Image Resolution



**Histogram in X of the 7 $\mu$ m pore MCP image at  $2 \times 10^6$  gain showing a few  $\mu$ m resolution.**

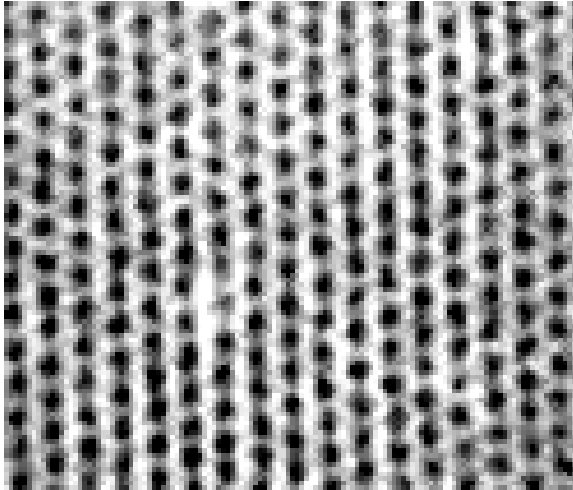


**Images of the 7 $\mu$ m pore MCP pair at  $2 \times 10^6$  gain showing multifiber boundaries and misaligned pores**

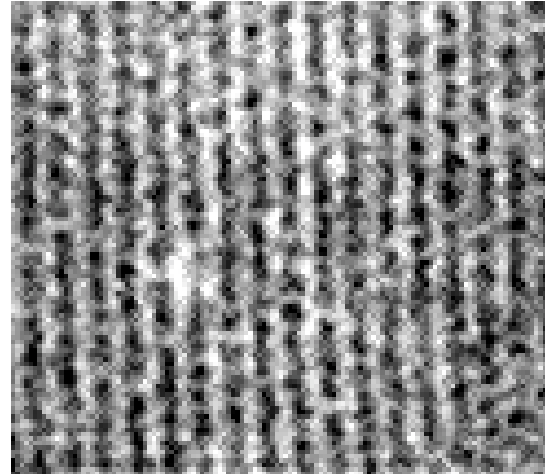


# 7 $\mu$ m MCP Detector Image Resolution

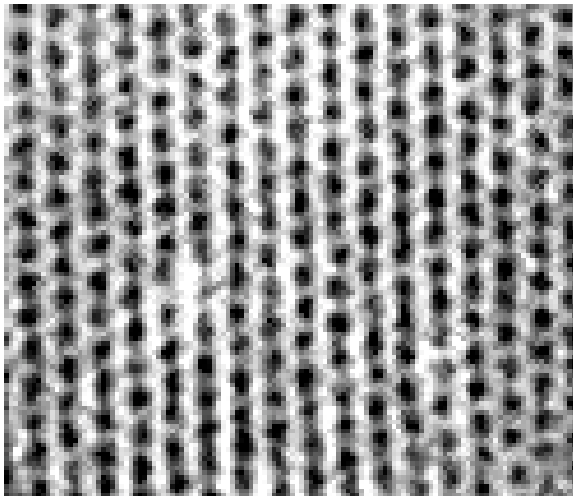
12 bits



9 bits



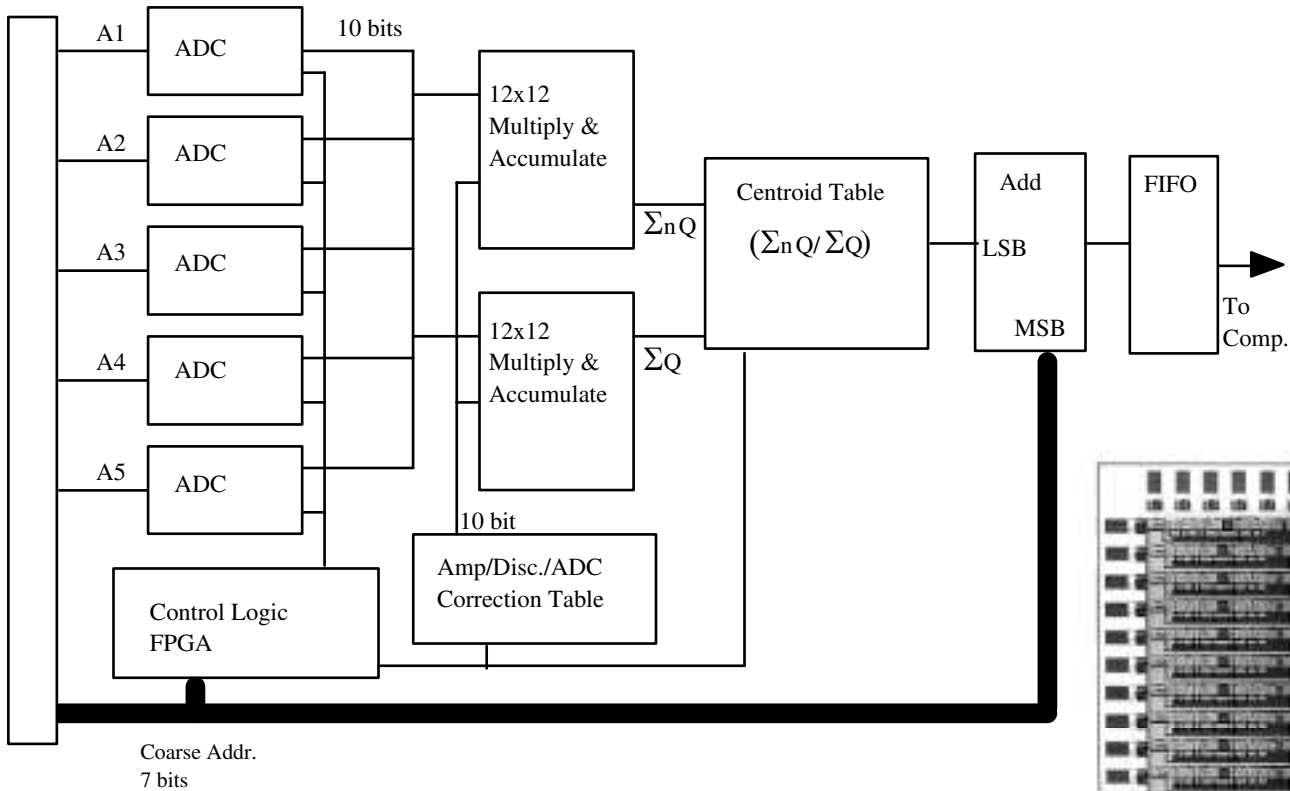
10 bits



**Image section of a 7 $\mu$ m MCP pair taken with the XS anode at different values of the signal digitization accuracy showing that the resolution does not degrade until 9 bits is reached.**

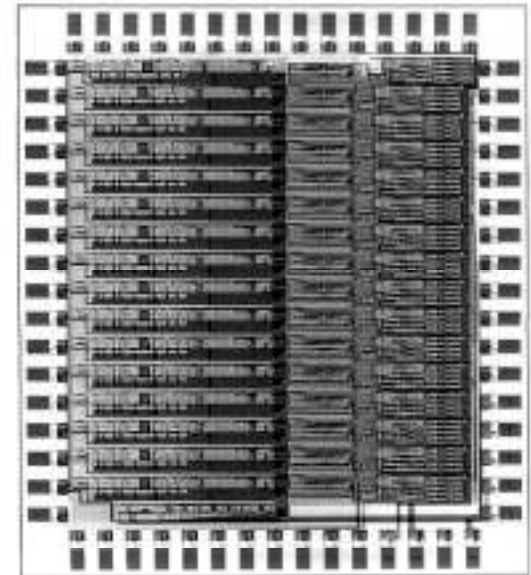


# Encoding Electronics Development Scheme



High speed hardware electronics chain downstream  
electronics can be implemented in standard modules  
Overall processing speed should support >10MHz rates

15 in /5 out, second generation amplifier design





# Integrated Cross Strip Anode Design

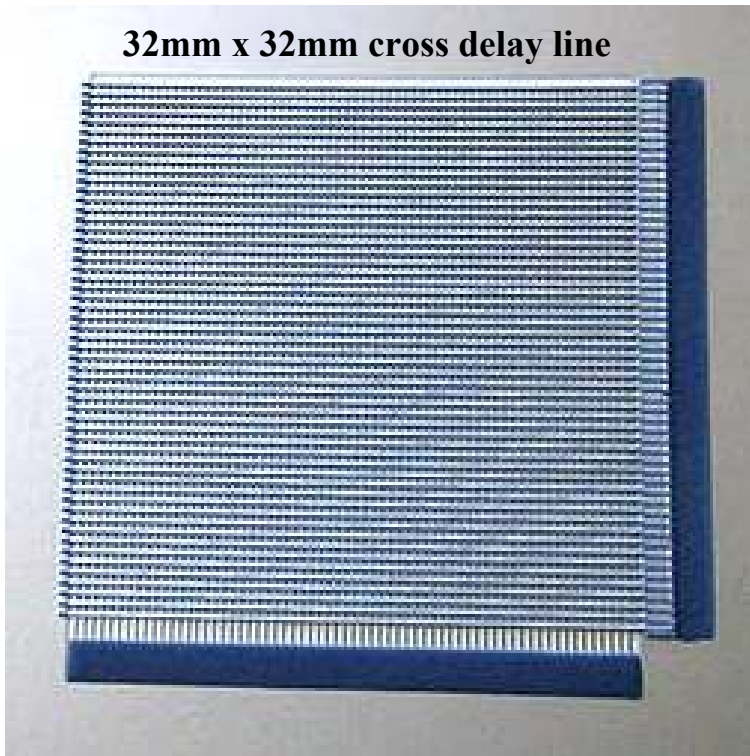
**Anodes up to 32 x 32mm have been made**

**Signals are routed to anode backside by hermetic vias**

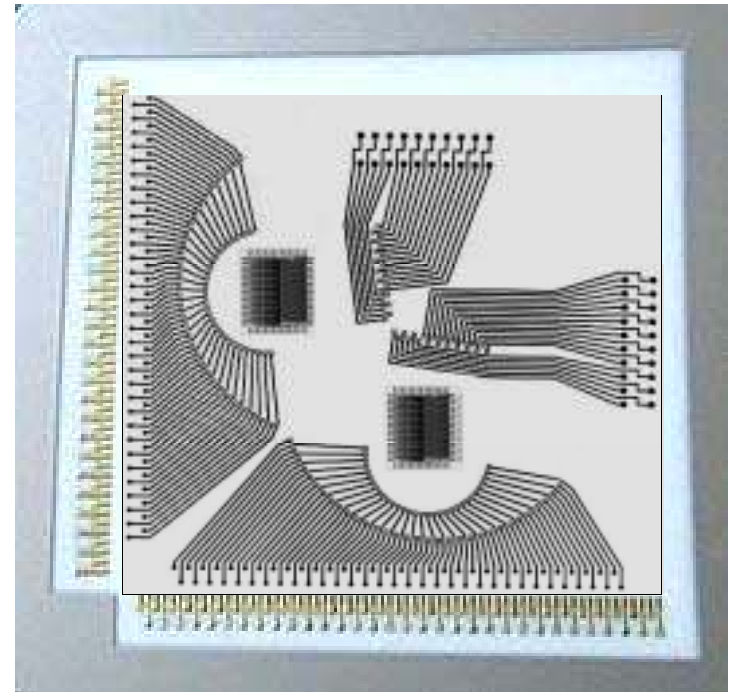
**Packaging can be compact with amp on anode backside**

**Anodes can be sealed to tube package with all electronics external**

32mm x 32mm cross delay line

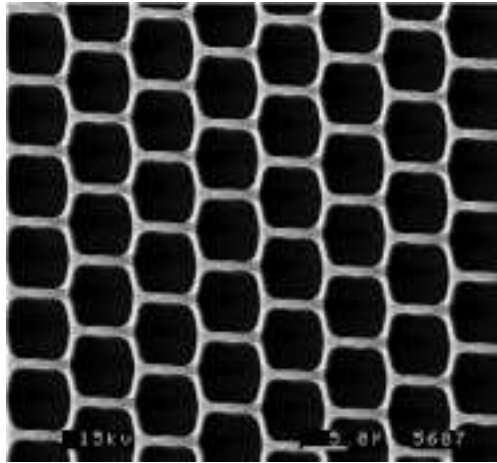


32mm x 32mm XS anode backside & proposed design showing fan-in, amp chip, & outputs

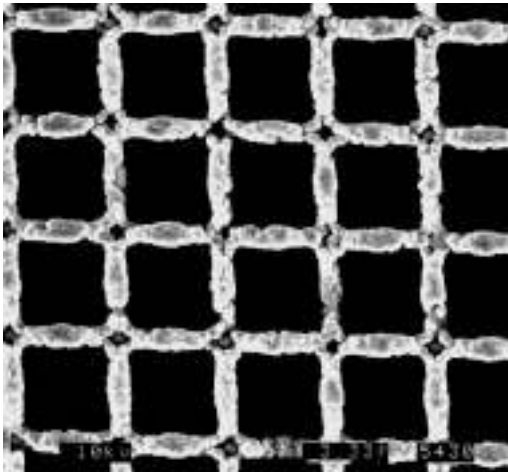




# Small Pore and Silicon MCP Developments



Hexagonal pore Si MCP with  $\sim 7\mu\text{m}$  pores,  $>75\%$  open area



Diamond coated Si MCP

## Small pore MCP's are now available (5 -6 $\mu\text{m}$ )

- Better spatial resolution - Faster response times
- Tight PHD at low gain - Lower background
- Now available in  $>100 \times 50\text{mm}$  formats

## Silicon MCP's

Silicon MCP's are made by photo-lithographic methods  
Photolithographic etch process - very uniform pore pattern  
No multifiber boundaries and array distortions of glass MCP's  
Scalable to large substrate sizes (200mm) with small pores ( $5\mu\text{m}$ )  
High temperature tolerance - CVD and "hot" processes OK  
UHV compatible, low background (No radioactivity)  
In collaboration with Nanosciences.

## Silicon microchannel plates in test program

25mm diameter (75mm currently feasible)

40:1 L/D ( $>100:1$  possible)

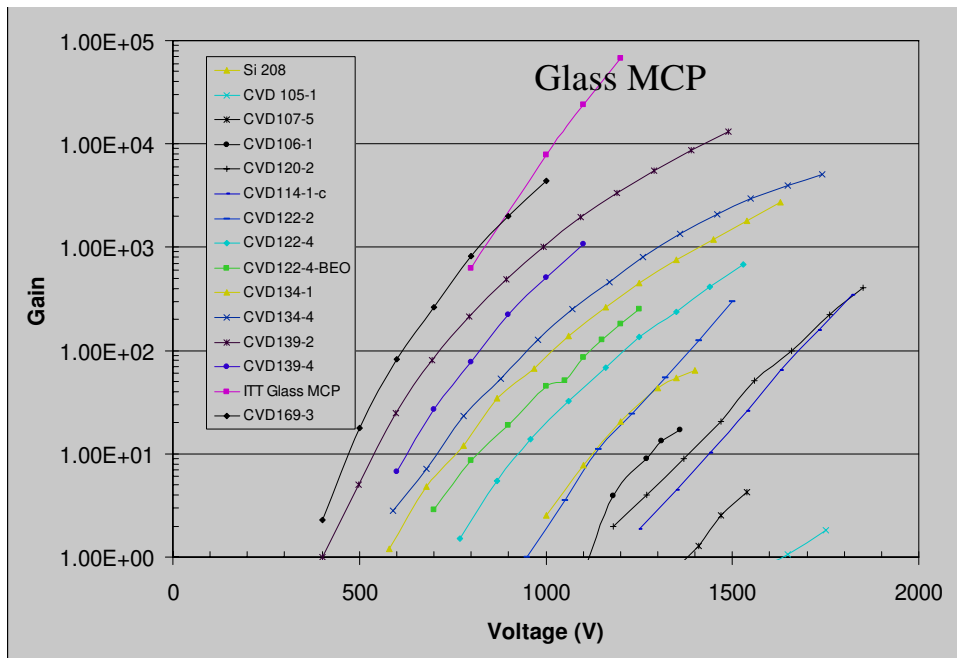
$7\mu\text{m}$  pore size, hexagonal and square pore

$\sim 2^\circ$  bias and  $8^\circ$  bias, resistances  $\sim \text{G}\Omega$ , to  $<100\text{M}\Omega$  possible

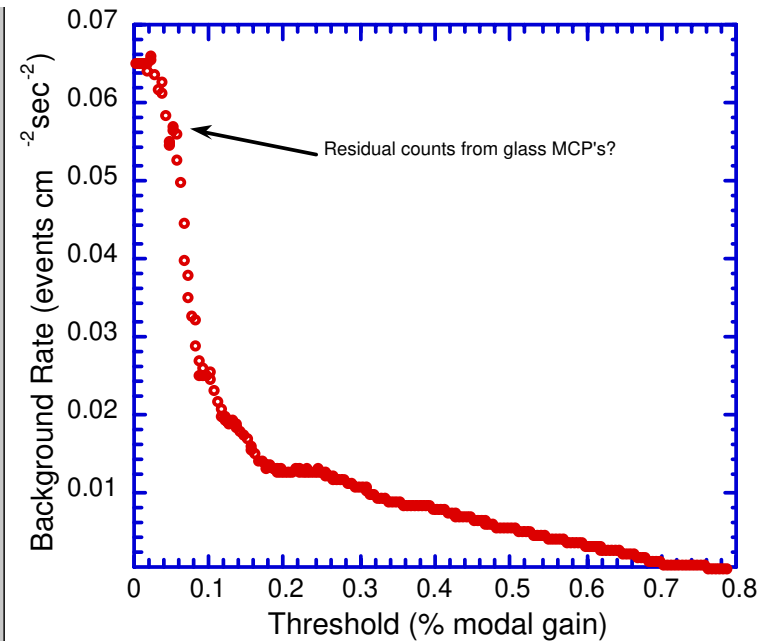


# Silicon MCP Performance Characteristics

- Many Si MCP's of 25mm diameter with  $\sim 7\mu\text{m}$  pores have been tested
- The performance is improving as production is being refined.
- Gain, quantum detection efficiency and pulse height are now very similar to glass MCP's
- Open area ratio is up to  $>75\%$  for hexagonal pores
- The background rate is lower ( $0.02 \text{ events cm}^{-2} \text{ sec}^{-1}$ ) than normal or low background glass
- CVD/MBE deposition of high temperature cathodes possible (Diamond made & measured)



Gain evolution of single Si MCP's



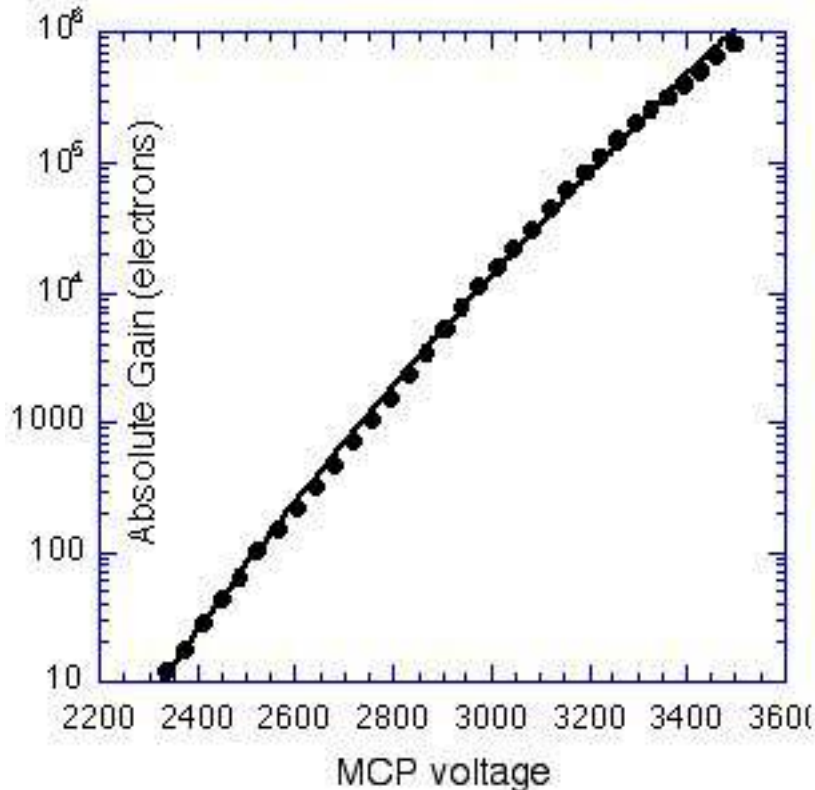
Si MCP background rate as a function of gain threshold.



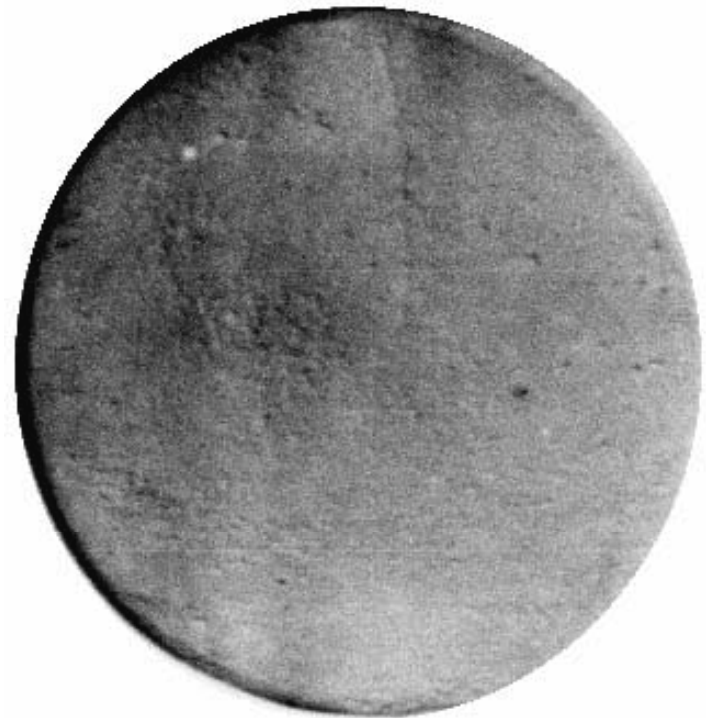
# Silicon MCP Performance Characteristics

*Gain and response uniformity are reasonably good.*

- *We have tested the first stacks of Si MCP's (4) with gain up to  $10^6$*
- *Scrubbing of Si MCP's shows a tendency for the gain to increase!*
- *Si MCP's lack of any periodic modulation in the flat field images but do show evidence of defects*



Gain curve for a stack of 4 back to back Si MCP's with  $6\mu\text{m}$  pores and 40:1 L/D.



An image of the fixed pattern response to a Hg vapor lamp with a stack of 4 Si MCP's.  $\sim 14\text{mm}$  area,  $10^7$  counts,  $\sim 50\mu\text{m}$  resolution XDL.



# Cross Strip Readout Status Summary

- $\sim 7\mu\text{m}$  pores are being resolved,  $< 3\mu\text{m}$  electronic resolution  
 $3\text{cm} = 10\text{k} \times 10\text{k} = 100 \times 10^6$  pixels!!!  
 $\$1/\text{pixel} = \$100 \times 10^6$  (ARISAKA!), will take  $\$0.01/\text{pixel}$ ,  $\$10^6$  bids!
- Image linearity is  $\sim 1\mu\text{m}$  level and shows pore misalignments
- Gain required is  $\sim 2 \times 10^6$ , allows higher local event rates
- Lower gain means longer overall lifetime
- Packaging can be compact with amp on anode
- 32mm anode format implemented, test with Si MCP's soon
  - **Development Plan**
- Fabrication of amp/disc/sparse chips
- Integrate downstream electronics into small package
- Power requirement of  $\sim 2\text{W}$  for 30mm readout
- High counting rates of 5MHz feasible
- Develop 40mm+ anode formats